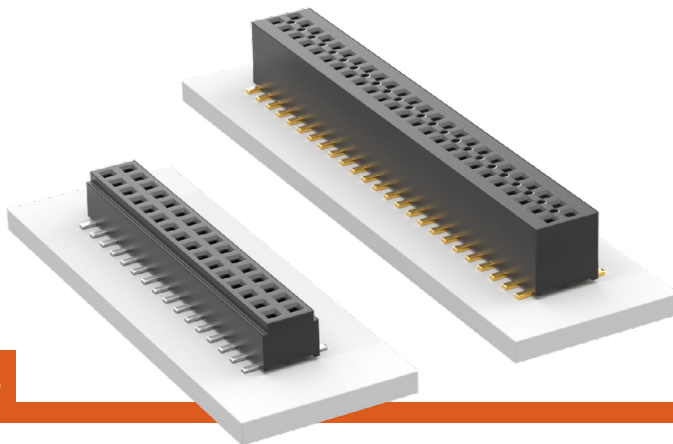


# RUGGED RELIABLE MICRO SOCKETS

(1.00 mm) .0394" PITCH • CLM/MLE SERIES



## CLM

### Mates:

FTM, FTMH, MW

## MLE

### Mates:

FTM, FTMH, MW

## SPECIFICATIONS

**Insulator Material:** Black LCP

**Contact Material:**

CLM: Phosphor Bronze

MLE: BeCu

**Plating:**

CLM: Au or Sn over

50  $\mu$ " (1.27  $\mu$ m) Ni

MLE: Au over 10  $\mu$ " (0.25  $\mu$ m) Ni

**Operating Temp Range:**

-55 °C to +125 °C

**Current Rating (CLM/FTMH):**

3.1 A per pin

(2 pins powered)

**Current Rating (MLE/FTMH):**

2.9 A per pin (2 pins powered)

**Max Cycles:**

CLM: 100 with 10  $\mu$ " (0.25  $\mu$ m) Au

**Voltage Rating:**

CLM: 270 VAC/382 VDC

MLE: 310 VAC/438 VDC

**Insertion Depth:**

CLM:

Top Entry = (1.40 mm) .055" min.,

Bottom Entry =

(2.41 mm) .095" min.

(Add board thickness for

correct post OAL)

MLE:

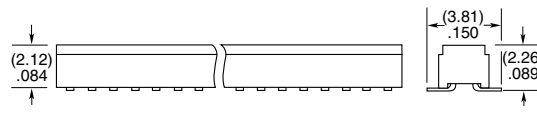
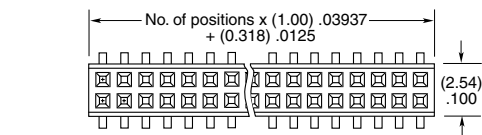
(1.63 mm) .064" to

(3.18 mm) .125" with

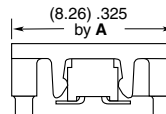
(0.38 mm) .015" wiper,

pass-through, or (2.44 mm) .096"

minimum for bottom entry



| PIN/ROW | A           |
|---------|-------------|
| 04-15   | (3.56) .140 |
| 16-50   | (7.11) .280 |



-PA

-P

## MLE

- 1

NO. PINS  
PER ROW

- 01

PLATING  
OPTION

- DV

OPTIONS

02 thru 50

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

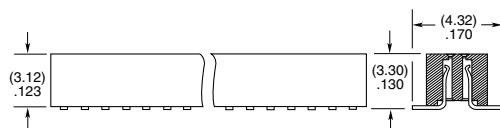
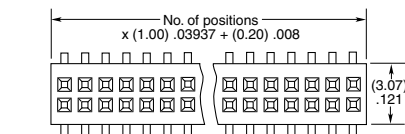
(0.10 mm) .004" max (02-25)

(0.15 mm) .006" max (26-50)\*

\*(.004" stencil solution

may be available; contact

ipg@samtec.com)



-G  
= 10  $\mu$ "  
(0.25  $\mu$ m)  
Gold

-A  
= Alignment Pin  
(3 positions minimum)  
Metal or plastic  
at Samtec discretion

-K  
= (4.00 mm) .1575" DIA  
Polyimide film  
Pick & Place Pad  
(5 positions minimum)

-P  
= Metal Pick & Place Pad  
(5 positions minimum)

-TR  
= Tape & Reel

-FR  
= Full Reel Tape & Reel  
(must order maximum  
quantity per reel;  
contact Samtec for  
quantity breaks)



-P

-A

## ALSO AVAILABLE

Contact Samtec

Alignment pin

Other Gold plating options



**Note:**  
Some lengths, styles and  
options are non-standard,  
non-returnable.